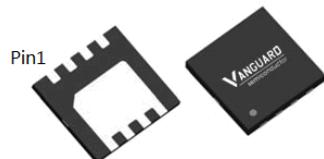


Features

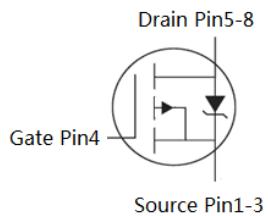
- P-Channel
- Very low on-resistance RDS(on) @ $V_{GS}=-4.5$ V
- 100 Avalanche Tested
- Fast Switching
- Repetitive Avalanche Allowed up to Tjmax
- Pb-free lead plating; RoHS compliant

V_{DS}	-30	V
$R_{DS(on),TYP}$ @ $V_{GS}=-10$ V	10	mΩ
$R_{DS(on),TYP}$ @ $V_{GS}=-4.5$ V	14	mΩ
I_D	-36	A

TDFN3.3x3.3



Part ID	Package Type	Marking	Tape and reel information
VSB012P03MS	TDFN3.3x3.3	012P03M	5000pcs/reel



Maximum ratings, at $T_j=25$ °C, unless otherwise specified

Symbol	Parameter	Rating	Unit	
Common Ratings (Tc=25°C Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage	±20	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-30	V	
T_J	Maximum Junction Temperature	150	°C	
T_{STG}	Storage Temperature Range	-55 to 150	°C	
I_S	Diode Continuous Forward Current	$T_c=25^\circ\text{C}$	-36	A
Mounted on Large Heat Sink				
I_D	Continuous Drain current @ $V_{GS}=-10$ V	$T_c=25^\circ\text{C}$	-36	A
		$T_c=100^\circ\text{C}$	-23	A
I_{DM}	Pulse Drain Current Tested ①	$T_c=25^\circ\text{C}$	-144	A
P_D	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	73	W
R_{JJC}	Thermal Resistance-Junction to Case	1.7	°C/W	
R_{JA}	Thermal Resistance Junction-Ambient	50	°C/W	
Drain-Source Avalanche Ratings				
EAS	Avalanche Energy, Single Pulsed ②	25	mJ	

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_D=-250\mu\text{A}$	-30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=-24\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	-1	μA
	Zero Gate Voltage Drain Current($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=-24\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	-100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=-250\mu\text{A}$	-1.0	-1.6	-2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=-10\text{V}$, $I_D=-20\text{A}$	--	10	12	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=-4.5\text{V}$, $I_D=-20\text{A}$	--	14	18	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-10\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	--	1980	--	pF
C_{oss}	Output Capacitance		--	350	--	pF
C_{rss}	Reverse Transfer Capacitance		--	285	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=-10\text{V}$, $I_D=-10\text{A}$, $V_{\text{GS}}=-10\text{V}$	--	28	--	nC
Q_{gs}	Gate-Source Charge		--	4.8	--	nC
Q_{gd}	Gate-Drain Charge		--	9	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-15\text{V}$, $I_D=-1\text{A}$, $R_G=6.8\Omega$, $V_{\text{GS}}=-10\text{V}$	--	9.6	--	nS
t_r	Turn-on Rise Time		--	10.5	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	22	--	nS
t_f	Turn-Off Fall Time		--	11	--	nS
Source- Drain Diode Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
I_{SD}	Source-drain current(Body Diode)	$T_c=25^\circ\text{C}$	--	--	-36	A
V_{SD}	Forward on voltage	$I_{\text{SD}}=-10\text{A}$, $V_{\text{GS}}=0\text{V}$	--	-0.82	-1.3	V
t_{rr}	Reverse Recovery Time	$T_j=25^\circ\text{C}$, $I_{\text{sd}}=-8\text{A}$, $V_{\text{GS}}=0\text{V}$ $dI/dt=-100\text{A}/\mu\text{s}$	--	26	--	nS
Q_{rr}	Reverse Recovery Charge			19		nC

NOTE:

① Repetitive rating; pulse width limited by max. junction temperature.

② Limited by $T_{J\text{max}}$, starting $T_J = 25^\circ\text{C}$, $L = 0.5\text{mH}$, $R_G = 25\Omega$, $I_{AS} = -10\text{A}$, $V_{GS} = -10\text{V}$. Part not recommended for use above this value

③ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

Typical Characteristics

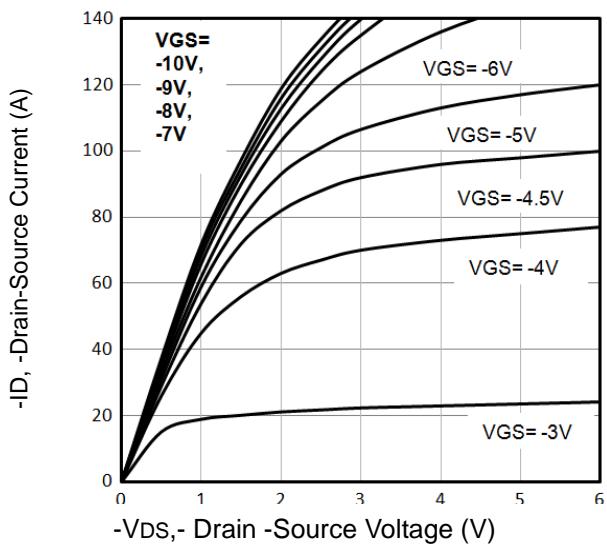


Fig1. Typical Output Characteristics

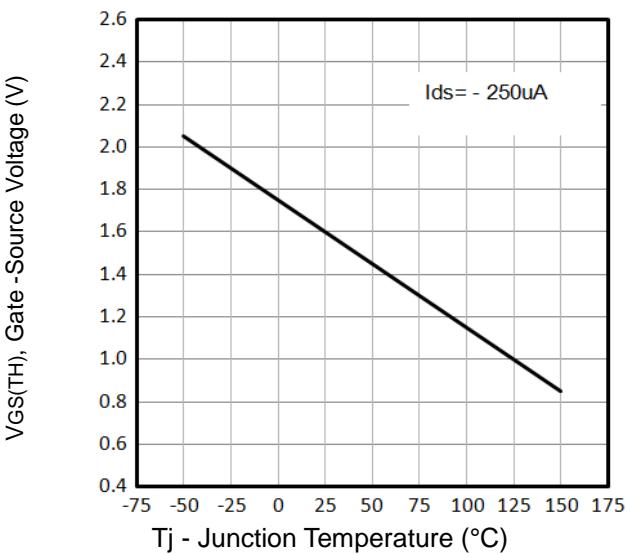


Fig2. Threshold Voltage Vs. Temperature

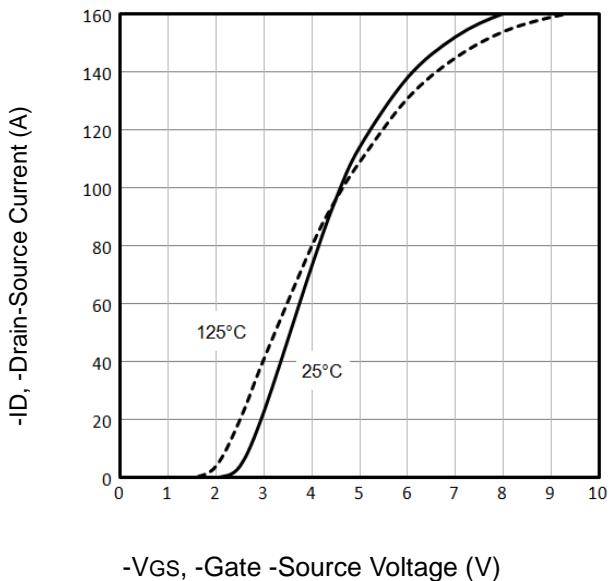


Fig3. Typical Transfer Characteristics

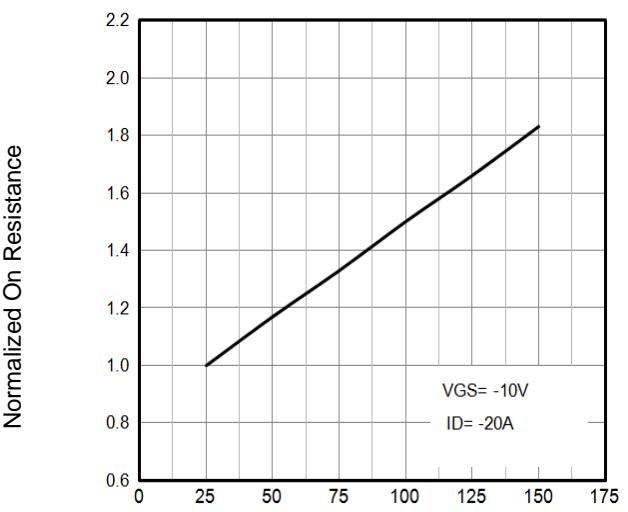


Fig4. Normalized On-Resistance Vs. Temperature

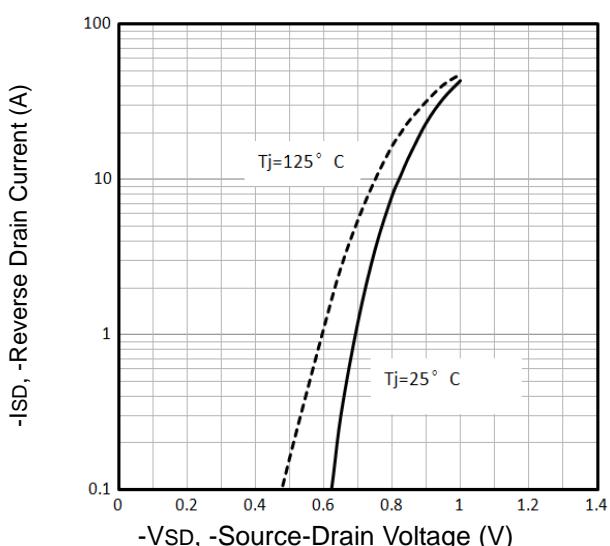


Fig5. Typical Source-Drain Diode Forward Voltage

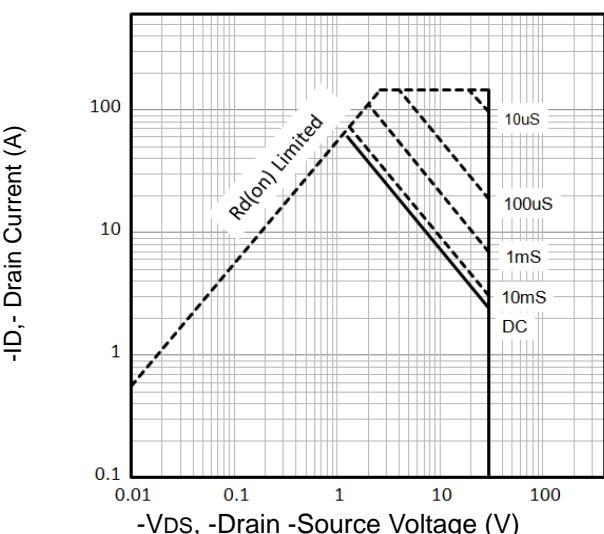


Fig6. Maximum Safe Operating Area

Typical Characteristics

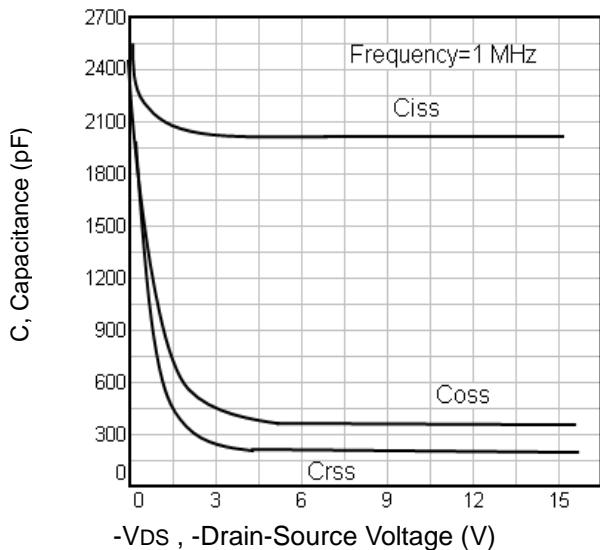


Fig7. Typical Capacitance Vs.Drain-Source Voltage

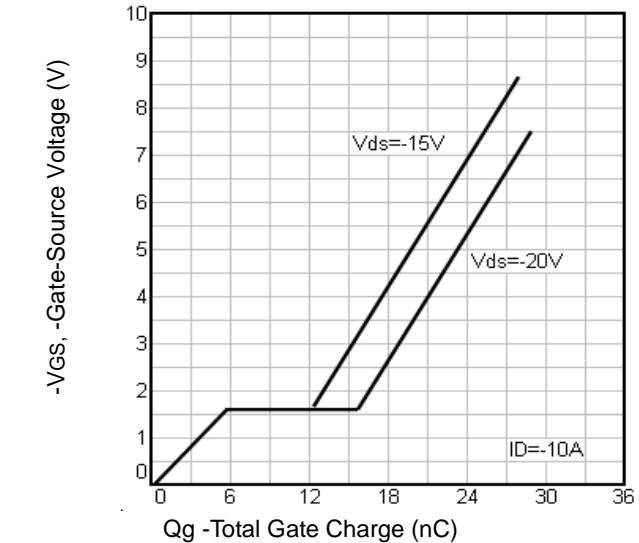


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

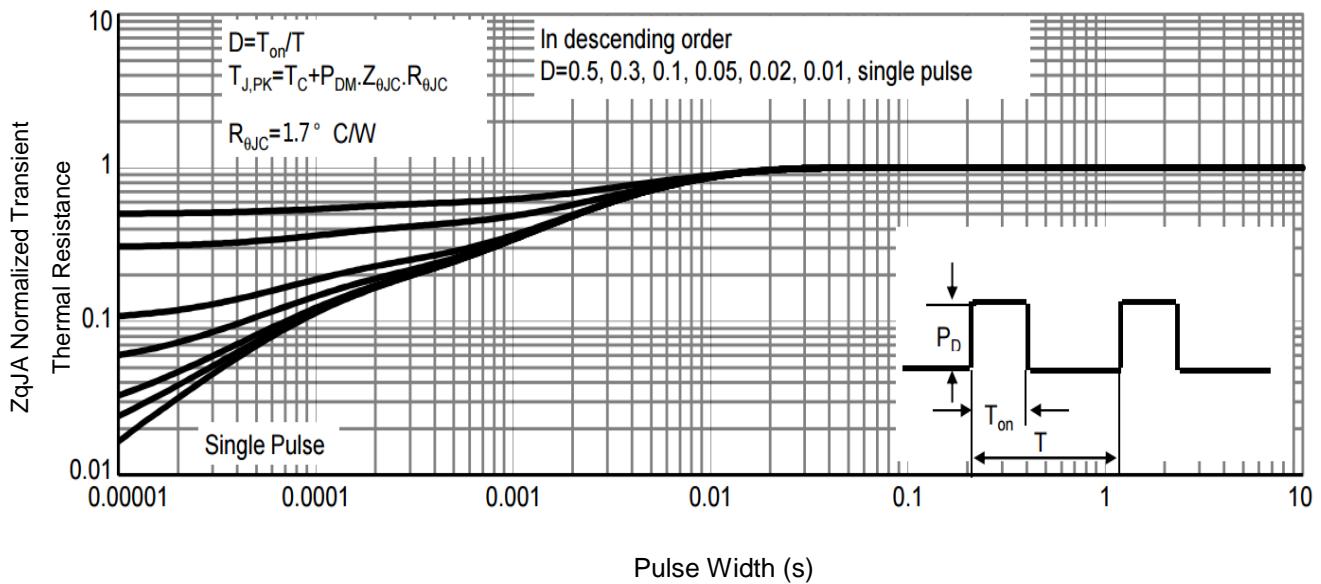


Figure 9: Normalized Maximum Transient Thermal

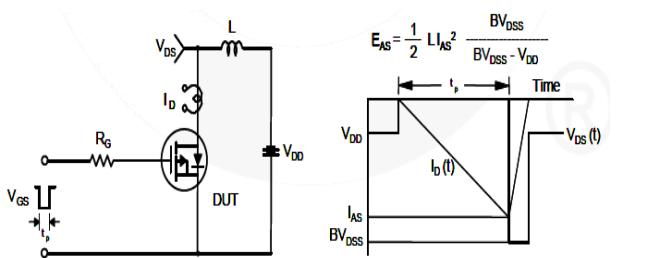


Fig10. Unclamped Inductive Test Circuit and Waveforms

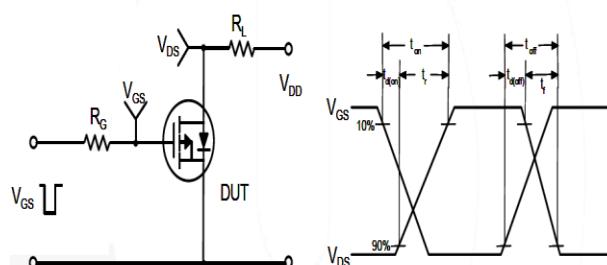
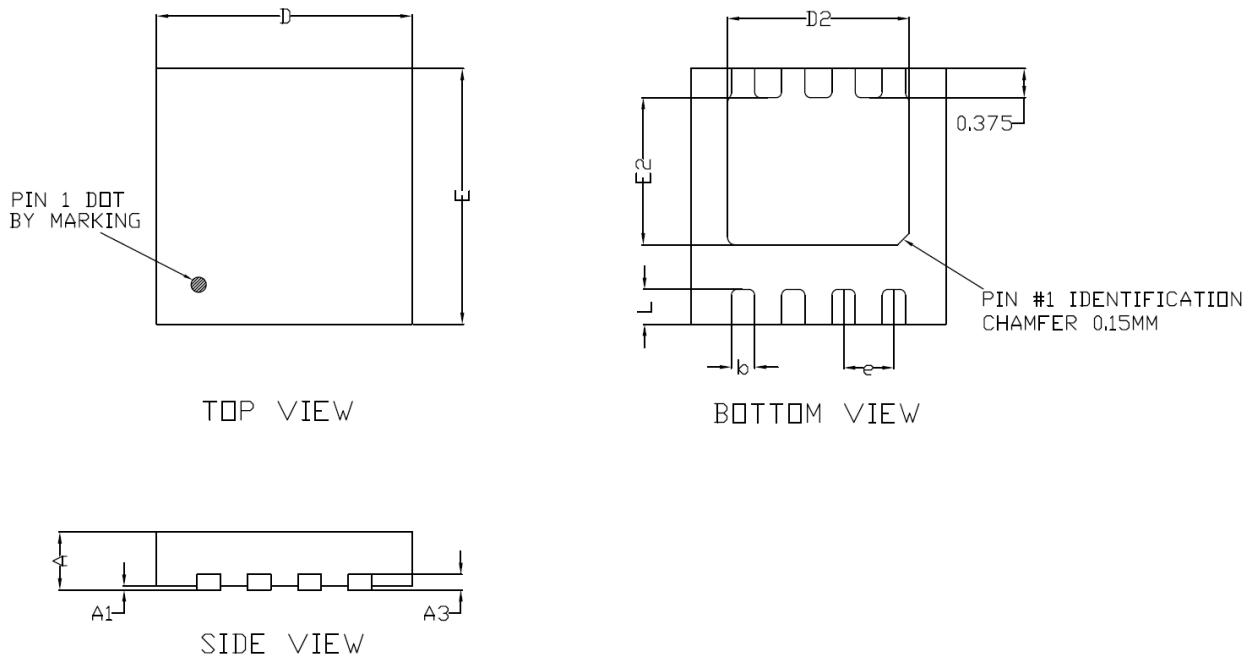


Fig11. Switching Time Test Circuit and waveforms

TDFN3.3x3.3 Package Outline Data



Lead finish : NiPdAu

DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.70	0.75	0.80	A1	0.00	--	0.05
A3	0.20 REF			D	3.25	3.30	3.35
E	3.25	3.30	3.35	D2	2.30	2.35	2.40
E2	1.85	1.90	1.95	b	0.25	0.30	0.35
L	0.35	0.45	0.55	e	0.65 BSC		

Customer Service

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